



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S):

Leitz et al.

SERIAL NO.:

10/647,074

GROUP NO.:

2812

FILING DATE:

August 22, 2003

EXAMINER:

Not Yet Assigned

TITLE:

Semiconductor Heterostructures and Related Methods

CERTIFICATE OF FIRST CLASS MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence, and any document(s) referred to as enclosed herein, is/are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 23 day of December, 2003.

Emily Walsk

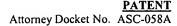
Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Submitted herewith are:

- 1. Transmittal Form (1 pg.);
- 2. Information Disclosure Statement (2 pgs.);
- 3. Form PTO-1449 (17 pgs.), with copies of cited references B1-B48 and C1-C131;
- 4. Return Receipt Postcard; and this
- 5. Certificate of First Class Mailing (1 pg.).

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1,2			Filing Date			August 22, 2003		
	A.		First Name		Le	Leitz		
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	FORM		Attorney D	ocket No.	AS	SC-058A		
			Patent No.	_	No	ot Applicable		
		Issue Date		No	ot Applicable			
		EN	CLOSURES (check all that apply)				
☐ F	Fee Transmittal Form			e to File Missing		Notice of Appeal to Board of Patent Appeals and Interferences		
	☐ Check Attached ☐ Copy of Fee Transmittal Form		Formal Drawi	ng(s)		Appeal Brief (in triplicate)		
	Amendment/Response		Request For C Examination (Transmittal			Status Inquiry		
	☐ Preliminary ☐ After Final ☐ Affidavits/declaration(s) ☐ Letter to Official		Power of Atto	Attorney		Return Receipt Postcard		
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	Petition for Extension of Time			laration and Power r Utility or Design ation		Additional Enclosure(s) (please identify below)		
⊠	Information Disclosure _Statement		Small Entity Statement					
	Form PTO-1449 Copies of IDS Citations (B1-B48 and C1-C131)		CD(s) for larg program	arge table or computer				
	Certified Copy of Priority Document(s)		Amendment A	After Allowance				
	Sequence Listing submission Request for Correction		ertificate of e of Correction (in					
CORI	RESPONDENCE ADDRESS			SIGNATURE BL	OCK			
Direct	Direct all correspondence to: Patent Administrator Testa, Hurwitz & Thibeaul High Street Tower 125 High Street Boston, MA 02110 Tel. No.: (617) 248-7000 Fax No.: (617) 248-7100			Date: December 23 Reg. No. 50,773 Tel. No.: (617) 248- Fax No.: (617) 248-	7453	Respectfully submitted, Mark L. Beletorodov Attorney for Applicants Testa, Hurwitz & Thibeault, LLP High Street Tower 125 High Street Boston, MA 02110		





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INFORMATION DISCLOSURE STATEMENT

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98 (a)(2)(i), only copies of the foreign patent documents and non-patent publications are enclosed.

It is respectfully requested that each of the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application.

In addition, Applicants wish to inform the Examiner about the following commonlyowned, co-pending patent applications, including all cited references and Office actions issued therein:

U.S. Serial Number	Filing Date	Inventor Name
09/611,024	July 6, 2000	Fitzgerald
10/268,025	October 9, 2002	Fitzgerald
10/268,425	October 10, 2002	Vineis et al.

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed before the mailing of the first Office action on the merits. Applicants believe no fees are due for this paper to be entered and considered, but the Commissioner is hereby authorized to charge Deposit Account No. 20-0531 for any required fees that may be due.

Information Disclosure Statement Serial No. 10/647,074 Page 2 of 2

Date: December <u>23</u>, 2003 Reg. No. 50,773

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2727902

Respectfully submitted,

Mark L. Beloborodov Attorney for Applicants

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INFORMATION DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.: ASC-058A

APPLICANT(S): Leitz et al.

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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	ΑI	2001/0003364	06/14/2001	Sugawara et al.		-	
	A2	2001/0014570	08/16/2001	Wenski et al.	1 1		
	A3	2002/0043660	04/18/2002	Yamazaki et al.			
	A4	2002/0052084	05/02/2002	Fitzgerald			
	A5	2002/0084000	07/04/2002	Fitzgerald			
	A6	2002/0096717	07/25/2002	Chu et al.			
	A7	2002/0100942	08/01/2002	Fitzgerald et al.			
	A8	2002/0123167	09/05/2002	Fitzgerald			
	A9	2002/0123183	09/05/2002	Fitzgerald	1.		
	A10	2002/0123197	09/05/2002	Fitzgerald et al.			
	A11	2002/0125471	09/12/2002	Fitzgerald et al.			
	A12	2002/0125497	09/12/2002	Fitzgerald			
· · · · · · · · · · · · · · · · · · ·	A13	2002/0168864	11/14/2002	Cheng et al.			
	A14	2002/0185686	12/12/2002	Christiansen et al.			
	A15	2003/0003679	01/02/2003	Doyle et al.			
	A16	2003/0013323	01/16/2003	Hammond et al.			
	A17	2003/0025131	02/06/2003	Lee et al.			
J	A18	2003/0034529	02/20/2003	Fitzgerald et al.			
	A19	2003/0041798	03/06/2003	Wenski et al.	1		
i	A20	2003/0057439	03/27/2003	Fitzgerald	-		
	A21	2003/0077867	04/24/2003	Fitzgerald			
	A22	2003/0102498	06/05/2003	Braithwaite et al.			
	A23	2003/0127646	07/10/2003	Christiansen et al.			
	A24	2003/0186073	10/02/2003	Fitzgerald			03/18/2003
	A25	4,010,045	03/01/1977	Ruehrwein			
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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A52	5,310,451	05/10/1994	Tejwani et al.		<u> </u>	
	A53	5,316,958	05/31/1994	Meyerson			
	A54	5,346,848	09/13/1994	Grupen- Shemansky et al.			
	A55	5,374,564	12/20/1994	Bruel			
	A56	5,399,522	03/21/1995	Ohori			
_	A57	5,413,679	05/09/1995	Godbey			
	A58	5,424,243	06/13/1995	Takasaki			
	A59	5,425,846	06/20/1995	Koze et al.			
	A60	5,426,069	06/20/1995	Selvakumar et al.	<u> </u>		
	A61	5,426,316	06/20/1995 .	Mohammad]		
	A62	5,442,205	08/15/1995	Brasen et al.			
	A63	5,461,243	10/24/1995	Ek et al.			
	A64	5,461,250	10/24/1995	Burghartz et al.			
	A65	5,462,883	10/31/1995	Dennard et al.			
	A66	5,476,813	12/19/1995	Naruse			
	A67	5,479,033	12/26/1995	Baca et al.			
	A68	5,484,664	01/16/1996	Kitahara et al.			
	A69	5,523,243	06/04/1996	Mohammad			
	A70	5,523,592	06/04/1996	Nakagawa et al.			
	A71	5,534,713	07/09/1996	Ismail et al.			
	A72	5,536,361	07/16/1996	Kondo et al.			
	A73	5,540,785	07/30/1996	Dennard et al.			
	A74	5,596,527	01/21/1997	Tomioka et al.			
	A75	5,617,351	04/01/1997	Bertin et al.	*		
	A76	5,630,905	05/20/1997	Lynch et al.			
	A77	5,633,516	05/27/1997	Mishima et al.			
	A78	5,659,187	08/19/1997	Legoues et al.			
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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A79	5,683,934	11/04/1997	Candelaria			
	A80	5,698,869	12/16/1997	Yoshimi et al.		· · · · · · · · · · · · · · · · · · ·	
<u> </u>	A81	5,714,777	02/03/1998	Ismail et al.			
	A82	5,728,623	03/17/1998	Mori			
	A83	5,739,567	04/14/1998	Wong			
	A84	5,759,898	06/02/1998	Ek et al.			
	A85	5,777,347	07/07/1998	Bartelink			
	A86	5,786,612	07/28/1998	Otani et al.			
	A87	5,786,614	07/28/1998	Chuang et al.			
	A88	5,792,679	08/11/1998	Nakato			
	A89	5,801,085	09/01/1998	Kim et al.			
	A90	5,808,344	09/15/1998	Ismail et al.			
	A91	5,810,924	09/22/1998	Legoues et al.			
	A92	5,828,114	10/27/1998	Kim et al.			
	A93	5,847,419	12/08/1998	Imai et al.			
	A94	5,859,864	01/12/1999	Jewell			
	A95	5,877,070	03/02/1999	Goesele et al.			
	A96	5,891,769	04/06/1999	Liaw et al.			
<u> </u>	A97	5,906,708	05/25/1999	Robinson et al.			
	A98	5,906,951	05/25/1999	Chu et al.			
	A99	5,912,479	06/15/1999	Mori et al.			
	A100	5,943,560	08/24/1999	Chang et al.			
	A101	5,963,817	10/05/1999	Chu et al.			
	A102	5,966,622	10/12/1999	Levine et al.			
	A103	5,998,807	12/07/1999	Lustig et al.			
	A104	6,010,937	01/04/2000	Karam et al.			
	A105	6,013,134	01/11/2000	Chu et al.			
	A106	6,030,884	02/29/2000	Mori			
	A107	6,033,974	03/07/2000	Henley et al.			
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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A108	6,033,995	03/07/2000	Muller			
· ·	A109	6,039,803	03/21/2000	Fitzgerald et al.			
	A110	6,058,044	05/02/2000	Sugiura et al.			
	A111	6,059,895	05/09/2000	Chu et al.			
	A112	6,074,919	06/13/2000	Gardner et al.			
	A113	6,096,590	08/01/2000	Chan et al.			
	A114	6,103,559	08/15/2000	Gardner et al.			
	A115	6,107,653	08/22/2000	Fitzgerald			
	A116	6,111,267	08/29/2000	Fischer et al.			
	A117	6,117,750	09/12/2000	Bensahel et al.			
	A118	6,124,614	09/26/2000	Ryum et al.			
<u>.</u>	A119	6,130,453	10/10/2000	Mei et al.			
	A120	6,133,799	10/17/2000	Favors et al.			
	A121	6,140,687	10/31/2000	Shimomura et al.			
	A:122	6,143,636	11/07/2000	Forbes et al.			
	A123	6,153,495	11/28/2000	Kub et al.			
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	A128	6,191,006	02/20/2001	Mori			
	A129	6,191,007	02/20/2001	Matsui et al.			
	A130	6,191,432	02/20/2001	Sugiyama et al.			
	A131	6,194,722	02/27/2001	Fiorini et al.			
	A132	6,204,529	03/20/2001	Lung et al.			
	A133	6,207,977	03/27/2001	Augusto	<u> </u>		
	A134	6,210,988	04/03/2001	Howe et al.			
	A135	6,218,677	04/17/2001	Broekaert	1		
•	A136	6,232,138	05/15/2001	Fitzgerald et al.			
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U.S. PATENT DOCUMENTS FILING DATE IF NAME **CLASS** SUB DOCUMENT DATE EXAM. **CLASS** APPROPRIATE INIT. NUMBER 06/05/2001 Kub et al. A138 6,242,324 6,249,022 06/19/2001 Lin et al. A139 06/26/2001 Furukawa et al. A140 6,251,755 Gehrke et al. 07/17/2001 A141 6,261,929 07/24/2001 Harari et al. A142 6,266,278 Schmitz et al. 6,271,551 08/07/2001 A143 Fransis et al. 08/07/2001 A144 6,271,726 09/18/2001 Fitzgerald 6,291,321 A145 Kibbel et al. 11/06/2001 A146 6,313,016 11/13/2001 Kant A147 6,316,301 Kub et al. 11/27/2001 A148 6,323,108 Lo et al. 12/11/2001 A149 6,329,063 01/01/2002 Tsuda et al. 6,335,546 A150 6,339,232 01/15/2002 Takagi A151 Chu et al. 02/26/2002 6,350,993 A152 04/09/2002 Nishinaga 6,368,733 A153 04/16/2002 Thornton et al. 6,372,356 A154 Kubo et al. 06/04/2002 A155 6,399,970 06/11/2002 Brunner et al. A156 6,403,975 Yanagisawa A157 06/18/2002 6,406,589 06/18/2002 Tezuka 6,407,406 A158 Akatsuka et al. 6,420,937 07/16/2002 A159 07/30/2002 Chu et al. A160 6,425,951 08/06/2002 Rim 6,429,061 A161 Billington et al. A162 6,482,749 11/19/2002 Fitzgerald A163 01/07/2003 6,503,773 02/04/2003 Christiansen et al. A164 6,515,335 Fitzgerald A165 02/11/2003 6,518,644 DATE CONSIDERED **EXAMINER**



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ATTORNEY DOCKET NO.: ASC-058A

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U.S. PATENT DOCUMENTS

EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A166	6,521,041	02/18/2003	Wu et al.			
	A167	6,525,338	02/25/2003	Mizushima et al.			
	A168	6,555,839	04/29/2003	Fitzgerald			
	A169	6,573,126	06/03/2003	Cheng et al.			
	A170	6,576,532	06/10/2003	Jones et al.			
·	A171	6,583,015	06/24/2003	Fitzgerald et al.			
	A172	6,593,191	07/15/2003	Fitzgerald			
	A173	6,594,293	07/15/2003	Bulsara et al.			
	A174	6,602,613	08/05/2003	Fitzgerald			
	A175	6,603,156	08/05/2003	Rim	1	1	

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EXAM. INIT.		DOCUMENT NUMBER	DATE	COUNTI CODE	RY CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
	Bl	41 01 167	07/23/1992	DE	· ·			N a	Abstract
	B2	0 514 018	11/19/1992	EP				N	Y
	B3	0 587 520	03/16/1994	EP				N	Y
	B4	0 683 522	11/22/1995	EP				N	Y
	B5	0 828 296	03/11/1998	EP				N	Y
	B6	0 829 908	03/18/1998	EP				N	Y
	B7	0 838 858	04/29/1998	EP				N	Abstract
	B8	1 020 900 /	07/19/2000	EP		1		N	Y
	B9	1 174 928	01/23/2002	EP		<u> </u>		N	Y
	B10	2 342 777	04/19/2000	GB				Y	Y
	B11	4-307974	10/30/1992	JP				N	Abstract
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-	B12 5-166724	07/02/1993	JP		<u> </u>		N	Abstract
	B13 6-177046	06/24/1994	JP				N '	Abstract
	B14 6-244112	09/02/1994	JP .		-		Y	Y
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	B15 6-252046	09/09/1994 -	JP				Y	Y
	B16 7-94420	04/07/1995	JP				N	Abstract
	B17 7-106446	04/21/1995	JP				N	Abstract
	B18 7-240372	09/12/1995	JP	 	· ·		N	Abstract
	B19 10-270685	10/09/1998	JP				N	Y
	B20 11-233744	08/27/1999	JP				N	Abstract
	B21 63-73398	04/02/1988	JP				N	N
	B22 2000-021783	01/21/2000	JP	-			N	Y
	B23 2000-031491	01/28/2000	JP				N	Y
	B24 2000-513507	10/10/2000	JP				Y	Y
	B25 2001-319935	11/16/2001	JP	-			N	Y
	B26 2002-076334	03/15/2002	JP				N	Y
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	B28 2002-289533	10/04/2002	JP				N	Y
	B29 2002-356399	12/13/2002	JP			-	N	Y
·	B30 2003-520444	07/02/2003	JP				N	Abstract
	B31 98/59365	12/30/1998	wo				N	Y
	B32 99/53539	10/21/1999	wo				N	Y
•	B33 00/48239	08/17/2000	wo				N	Y
	B34 00/54338	09/14/2000	wo		1-44		N	Y
	B35 01/022482	03/29/2001	wo				N	Y
	B36 01/54175	07/26/2001	wo	 			N	Υ .

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FOREIGN PATENT DOCUMENTS ENGLISH COUNTRY FILING **ABSTRACT** DOCUMENT CLASS SUB EXAM. DATE LANG DATE ONLY INIT. NUMBER CODE **CLASS** (Y/N) wo N B37 01/54202 07/26/2001 Y B38 01/93338 12/06/2001 WO Y wo Ν B39 \01/99169 12/27/2001 wo N Y 09/12/2002 B40 _02/071488 $\overline{\mathbf{Y}}$ wo N B41 02/071491 09/12/2002 WO 09/12/2002 02/071495 B42 Υ B43 02/082514 10/17/2002 WO N Y 02/14/2002 WO N 02/13262 B44 02/21/2002 wo Υ B45 02/15244 N Ÿ 04/04/2002 wo -02/27783 B46 Ÿ B47 02/47168 wo N 06/13/2002 Y N 02/20/2003 WO B48 03/015140 OTHER ART, JOURNAL ARTICLES, ETC. OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication) EXAM. INIT. Armstrong et al., "Design of Si/SiGe Heterojunction Complementary Metal-Oxide-Semiconductor Cl Transistors," IEDM Technical Digest (1995 International Electron Devices Meeting), pp. 761-764. Armstrong, "Technology for SiGe Heterostructure-Based CMOS Devices," PhD Thesis, Massachusetts C2 Institute of Technology, 1999, pp. 1-154. Augusto et al., "Proposal for a New Process Flow for the Fabrication of Silicon-Based Complementary MOD-MOSFETs without Ion Implantation," Thin Solid Films, Vol. 294, No. 1-2 (February 15, 1997), pp. 254-258. Barradas et al., "RBS analysis of MBE-grown SiGe/(001) Si heterostructures with thin, high Ge content SiGe C4 channels for HMOS transistors," Modern Physics Letters B, Vol. 15 (2001), abstract. Borenstein et al., "A New Ultra-Hard Etch-Stop Layer for High Precision Micromachining," Proceedings of the 1999 12th IEEE International Conference on Micro Electro Mechanical Systems (MEMs) (January 17-21, 1999), pp. 205-210. Bouillon et al., "Search for the optimal channel architecture for 0.18/0.12 μm bulk CMOS experimental study," IEEE (1996), pp. 21.2.1-21.2.4. DATE CONSIDERED **EXAMINER**



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